

*Claim*

a mold encapsulating said semiconductor light-emitting chip, said mold encapsulating said inner portion of at least one of said pair of electrodes, said outer portion of at least one of said pair of electrodes extending substantially laterally beyond said mold; and

a step formed in said inner portion of at least one of said pair of electrodes at an inside of said mold, said step having a height increasing from an outer side to an inner side of said mold.

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